

# Semiconductor Assembly and Testing Services 2017 Global Market Expected to Grow at CAGR 5.68 % and Forecast to 2021

*The report provides in depth study of "Semiconductor Assembly and Testing Services" using SWOT analysis Weakness, Opportunities and Threat to the organization*

PUNE, INDIA, November 2, 2017

/EINPresswire.com/ -- [Semiconductor Assembly and Testing Services Market Analysis And Forecast](#)

About Semiconductor Assembly and Testing Services

The number of electronic devices we use in our day-to-day life has been increasing in the past few decades. These devices range from simple media players, smartphones, laptops, and TVs to wearable smart watches and Internet of Things (IoT) devices such as connected thermostats, automated lighting, and remote health monitoring equipment. Semiconductor assembly and testing services (SATS) or outsourced semiconductor assembly and testing (OSAT) refers to the outsourcing of integrated circuit packaging and final product testing to third-party service providers.

Technavio's analysts forecast the global semiconductor assembly and testing services market to grow at a CAGR of 5.68% during the period 2017-2021.

Covered in this report

The report covers the present scenario and the growth prospects of the global semiconductor assembly and testing services market for 2017-2021. The report presents a detailed picture of the market by way of study, synthesis, and summation of data from multiple sources.

The market is divided into the following segments based on geography:

- Americas
- APAC
- EMEA

Technavio's report, Global Semiconductor Assembly and Testing Services Market 2017-2021, has been prepared based on an in-depth market analysis with inputs from industry experts. The report



covers the market landscape and its growth prospects over the coming years. The report also includes a discussion of the key vendors operating in this market.

#### Key vendors

- Amkor Technology
- ASE Group
- Jiangsu Changjiang Electronics Technology (JCET)
- Powertech Technology
- Siliconware Precision Industries (SPIL)

#### Other prominent vendors

- Chipbond Technology
- ChipMOS TECHNOLOGIES
- FormFactor
- Formosa Advanced Technologies
- King Yuan ELECTRONICS
- Lingsen Precision Industries
- PSi Technologies
- SIGNETICS
- Tessolve Semiconductor
- Tianshui Huatian Technology
- Unisem
- UTAC

#### Market driver

- Growth of cloud-based servers and big data services
- For a full, detailed list, view our report

#### Market challenge

- Highly cyclic nature of electronics industry
- For a full, detailed list, view our report

#### Market trend

- Growth of advanced system in package (SiP) modules
- For a full, detailed list, view our report

#### Key questions answered in this report

- What will the market size be in 2021 and what will the growth rate be?
- What are the key market trends?
- What is driving this market?
- What are the challenges to market growth?
- Who are the key vendors in this market space?

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